

## **Claims**

1. A method of fabricating a semiconductor chip package comprising the steps of:
  - providing a semiconductor wafer;
  - 5 applying a layer of nonconductive epoxy to a surface of said wafer using a screen printing process;
  - sawing said wafer to create a plurality of semiconductor dice; and
  - attaching at least one of said dice to a pad by means of said epoxy layer.
- 10 2. The method of Claim 1 wherein applying said epoxy layer comprises applying at least two epoxy sublayers.
3. The method of Claim 2 comprising hard curing a first epoxy sublayer before forming a second epoxy sublayer.
4. The method of Claim 2 comprising partially curing a final epoxy  
15 sublayer before bringing said final epoxy sublayer into contact with a leadframe.
5. The method of Claim 4 wherein partially curing said final epoxy sublayer comprises heating said final epoxy sublayer until it is in a soft solid state.
6. The method of Claim 4 wherein partially curing said final epoxy  
20 sublayer comprises heating said final epoxy sublayer to a temperature in the range of 100° C for a time duration of 60 seconds.
7. The method of Claim 4 wherein attaching at least one of said dice to a pad comprises heating heating said final epoxy sublayer to a temperature in the range of 110° C to 170° C for a time duration of 50 to 400 seconds.
- 25 8. The method of Claim 7 wherein attaching at least one of said dice to a pad comprises pressing said at least one die against said pad with a force in the range of 100 to 350 grams.
9. The method of Claim 4 wherein applying said epoxy layer comprises applying only two epoxy sublayers.

10. The method of Claim 9 comprising hard curing a first epoxy sublayer before forming a second epoxy sublayer and partially curing said second epoxy layer before bringing said second epoxy sublayer into contact with a leadframe.